

ABSTRACT OF THE DISCLOSURE

A semiconductor package is comprised of a substrate for mounting and fixing a semiconductor element thereon and a connecting pattern. The substrate is provided with a through hole formed therein. The semiconductor element is fixed with its surface where the element is formed being mounted on the substrate and with its electrode being within the through hole. The electrode of the semiconductor element is electrically connected to the connecting pattern via wires through the through hole. The through hole and the wires are sealed with resin.

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